

50A 1200V Trench Fieldstop IGBT with anti-parallel diode SRE50N120FSUD9
General Description

The SRE50N120FSUD9 is a Field Stop Trench IGBT with anti-parallel diode, which offers low switching losses, high energy efficiency and high avalanche ruggedness for soft switching applications such as UPS, solar inverters, industrial power supplies, etc.

The SRE50N120FSUD9 package is TO-247.

Features

- High Breakdown Voltage to 1200V
- Advanced Trench Fieldstop technology
 - Low $V_{CE(sat)}$
 - High Ruggedness, Temperature Stability
 - Easy Parallel Switching Capability due to Positive Temperature Coefficient in $V_{CE(SAT)}$
- Soft Current Turn-off Waveforms
- Enhanced Avalanche Capability
- Non-Automotive Qualified

Application

- Solar Inverters
- Uninterrupted Power Supply
- Industrial Power Supplies
- Grid Inverter

Ordering Information

SRE50N120FSUD9□□-□

Circuit Type		G: Green
Package		Blank: Tube
T: TO-247		TR: Tape & Reel

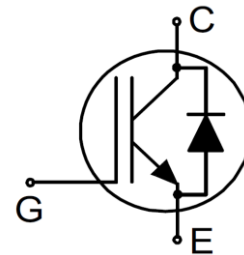
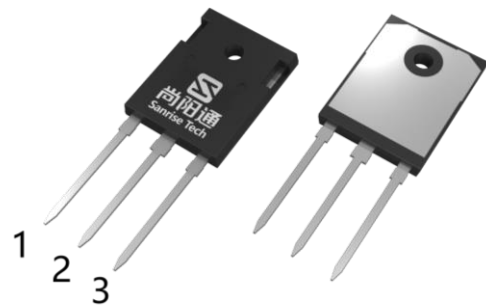
Symbol


Figure 1 Symbol of SRE50N120FSUD9

Package Type


TO-247

Pin 1- Gate; Pin 2&backside- Collector; Pin 3-Emitter

Figure 2 Package Type of SRE50N120FSUD9

Package	Part Number	Marking ID	Packing Type
TO-247	SRE50N120FSUD9T-G	SRE50N120FSUD9TG	Tube

50A 1200V Trench Fieldstop IGBT with anti-parallel diode SRE50N120FSUD9
Absolute Maximum Ratings

Parameter		Symbol	Rating	Unit
Collector-emitter voltage		V_{CES}	1200	V
Gate-emitter Voltage		V_{GES}	± 20	V
Transient Gate-emitter Voltage			± 30	V
Continuous Collector Current	$T_C=25^\circ\text{C}$	I_C	100	A
	$T_C=100^\circ\text{C}$		50	
Pulsed Collector Current, Limited by T_{Jmax}		I_{CM}	200	A
Diode Continuous Collector Current ($T_C=100^\circ\text{C}$)		I_F	50	A
Diode Pulsed Current, Limited by T_{Jmax}		I_{FM}	150	A
Power dissipation	$T_C=25^\circ\text{C}$	P_{tot}	500	W
	$T_C=100^\circ\text{C}$		250	W
Maximum Operating Junction Temperature		T_{Jmax}	175 ⁽¹⁾	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 ~ 150	$^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)		T_{LEAD}	260	$^\circ\text{C}$

Note:

1. Reliability testing conducted at $T_j=175^\circ\text{C}$.

Thermal Resistance

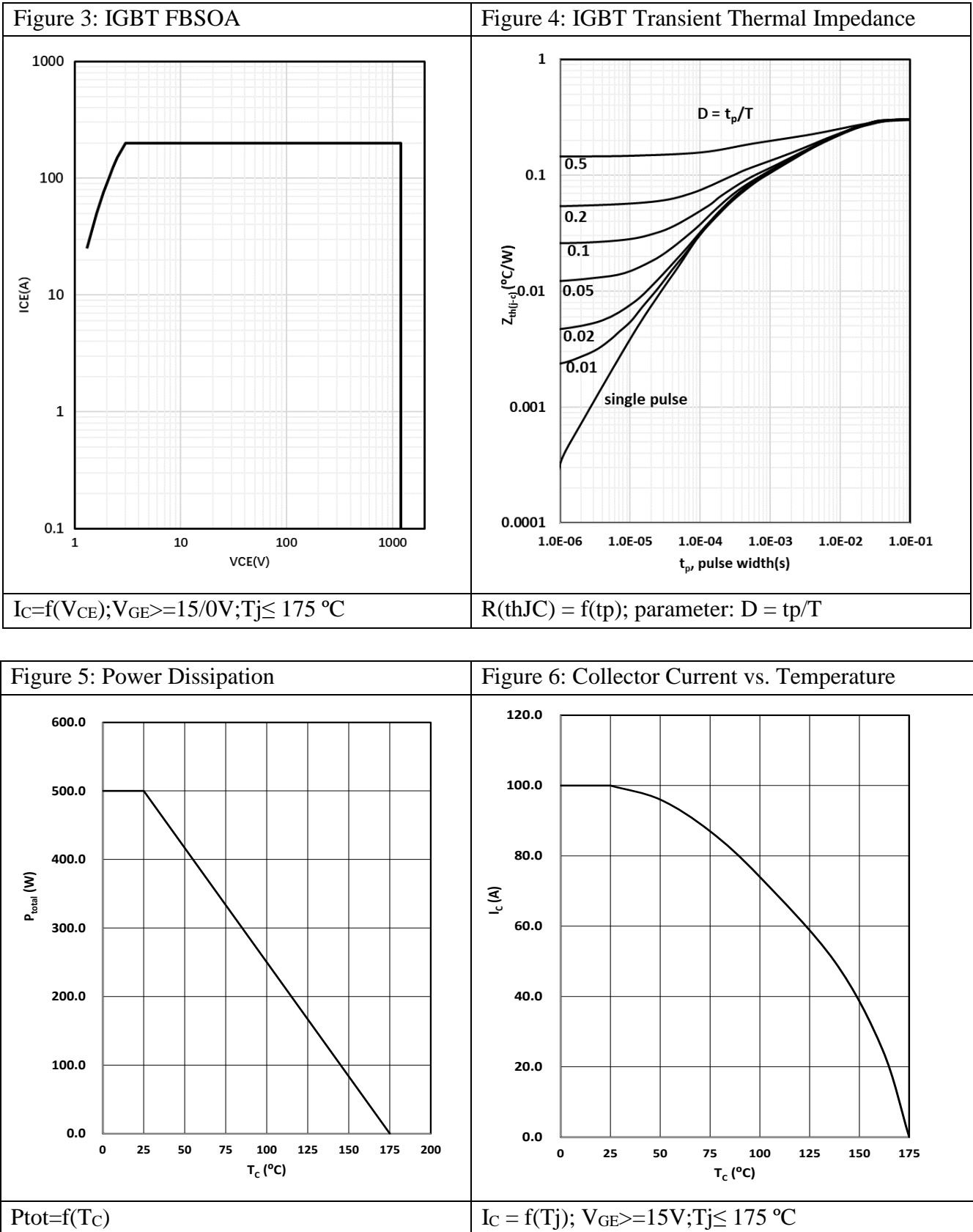
Parameter	Package	Symbol	Min	Typ	Max	Unit
IGBT thermal Resistance, Junction-to-Case	TO-247	R_{thJC}	-	-	0.3	$^\circ\text{C}/\text{W}$
Diode thermal Resistance, Junction-to-Case	TO-247	R_{thJC}	-	-	0.9	
Thermal Resistance, Junction-to-Ambient	TO-247	R_{thJA}	-	-	40	

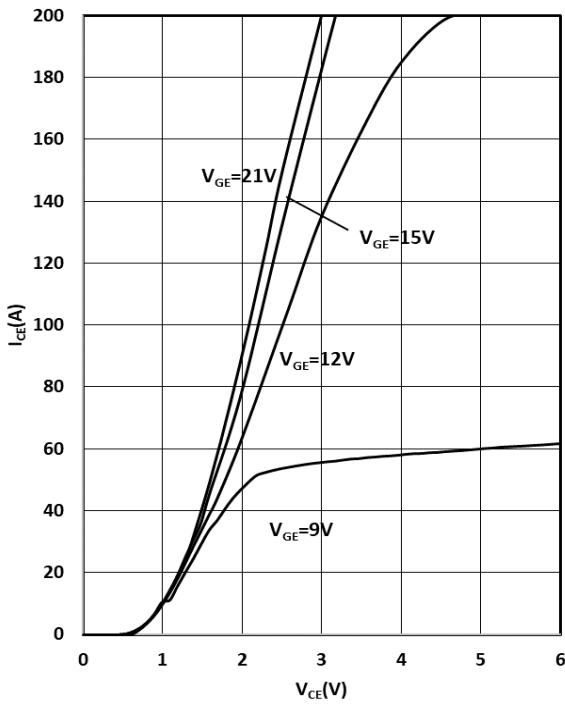
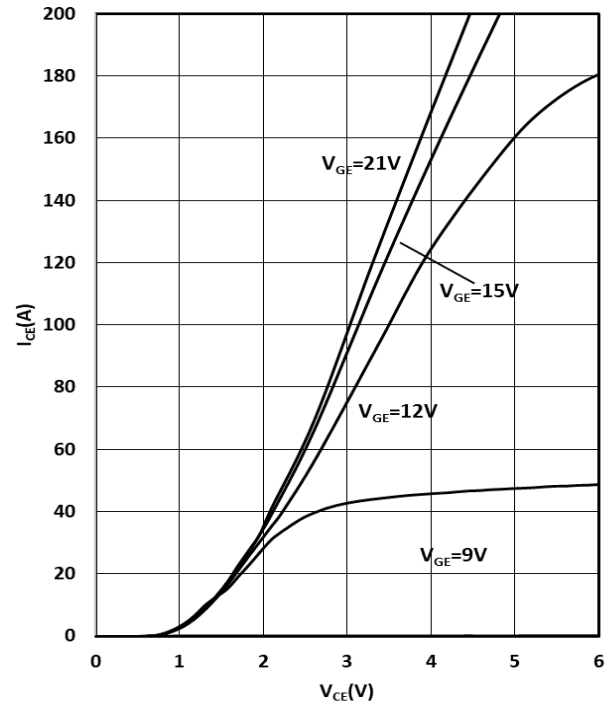
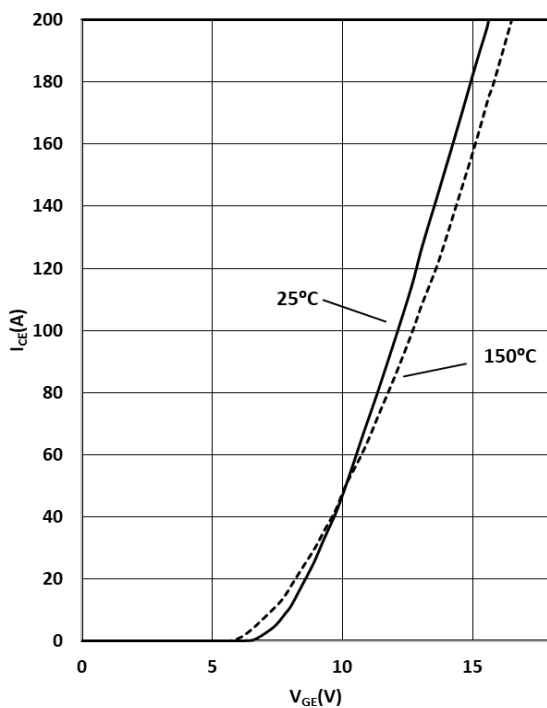
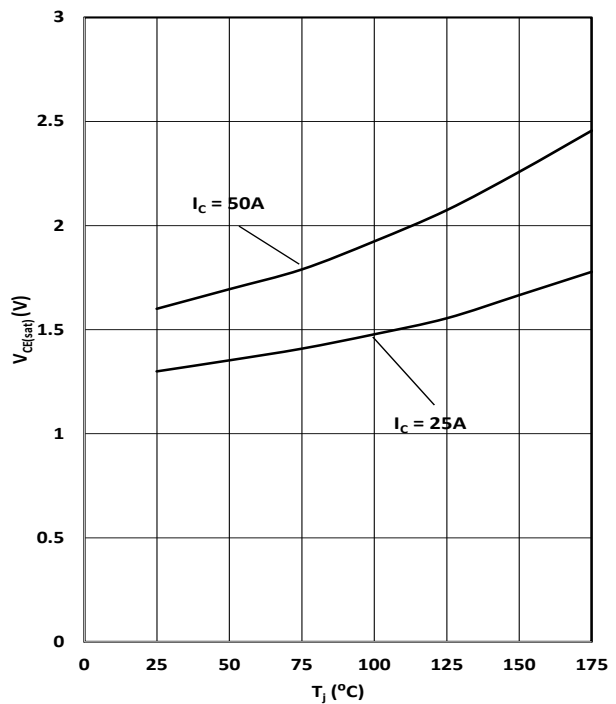
50A 1200V Trench Fieldstop IGBT with anti-parallel diode SRE50N120FSUD9
Electrical Characteristics
 $T_J = 25^\circ\text{C}$, unless otherwise specified.

Parameter		Symbol	Test Conditions	Min	Typ	Max	Unit	
Statistic Characteristics								
Collector-emitter Breakdown Voltage		BV_{CES}	$V_{GE}=0V, I_C=500\mu A$	1200			V	
Gate Threshold Voltage		$V_{GE(th)}$	$V_{CE}=V_{GE}, I_C=1.6mA$	4.6	5.4	6.2	V	
Collector-emitter saturation voltage		$V_{CE(sat)}$	$V_{GE}=15V, I_C=50A,$ $T_J=25^\circ\text{C}$		1.6	2.0	V	
			$T_J=125^\circ\text{C}$		2.0		V	
			$T_J=150^\circ\text{C}$		2.43		V	
Zero Gate Voltage Collector Current		I_{CES}	$V_{CE}=1200V, V_{GE}=0V$ $T_J=25^\circ\text{C}$			100	μA	
			$T_J=175^\circ\text{C}$			1	mA	
Gate-emitter Leakage Current	Forward	I_{GESF}	$V_{GE}=20V, V_{CE}=0V$			100	nA	
	Reverse	I_{GESR}	$V_{GE}=-20V, V_{CE}=0V$			-100	nA	
Dynamic Characteristics								
Input Capacitance		C_{IES}	$V_{CE}=25V, V_{GE}=0V,$ $f=1MHz$		4450		pF	
Output Capacitance		C_{OES}			215			
Reverse Transfer Capacitance		C_{RES}			26			
Gate Resistance		R_G	$f=1MHz, \text{Open Drain}$		1.2		Ω	
Turn-on Delay Time		$t_{d(on)}$	$T_J=25^\circ\text{C}$ $V_{CC}=600V, I_C=50A$ $R_G=10\Omega, V_{GE}=0/15V$ Energy losses include "tail" and diode reverse recovery		44		ns	
Rise Time		t_r			55		ns	
Turn-off Delay Time		$t_{d(off)}$			164		ns	
Fall Time		t_f			127		ns	
Turn-on energy		E_{on}			3.4		mJ	
Turn-off energy		E_{off}			1.6		mJ	
Total switching energy		E_{ts}			5.0		mJ	
Turn-on Delay Time		$t_{d(on)}$		$T_J=150^\circ\text{C}$ $V_{CC}=600V, I_C=50A$ $R_G=10\Omega, V_{GE}=0/15V$ Energy losses include "tail" and diode reverse recovery		60.4		ns
Rise Time		t_r				46.4		ns
Turn-off Delay Time		$t_{d(off)}$				302		ns
Fall Time		t_f			196		ns	
Turn-on energy		E_{on}			4.3		mJ	
Turn-off energy		E_{off}			2.1		mJ	
Total switching energy		E_{ts}			6.4		mJ	
Gate to Emitter Charge		Q_{GE}	$V_{CC}=600V, I_C=50A$ $V_{GE}=0 \text{ to } 15V$			62		nC
Gate to Collector Charge		Q_{GC}				170		
Gate Charge Total		Q_G				410		

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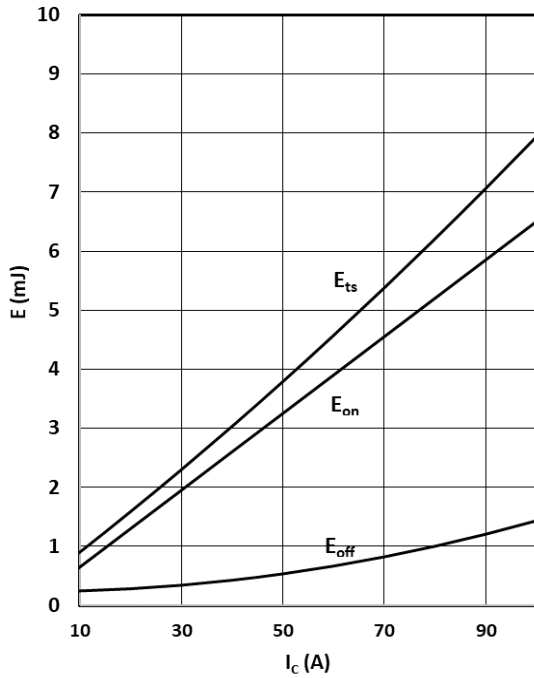
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Diode Characteristics						
Diode Forward Voltage	V_F	$I_F=25A$ $T_J=25^\circ C$		1.99	2.6	V
		$I_F=25A$ $T_J=125^\circ C$		1.78		
		$I_F=25A$ $T_J=175^\circ C$		1.69		
		$I_F=50A$ $T_J=25^\circ C$		2.2	2.8	
		$I_F=50A$ $T_J=125^\circ C$		2.0		
		$I_F=50A$ $T_J=175^\circ C$		1.9		
Reverse Recovery Time	t_{rr}	$V_R=600V, I_F=50A$ $dI_F/dt=660A/us$		75		ns
Reverse Recovery Charge	Q_{rr}			803		nC
Peak Reverse Recovery Current	I_{rrm}			17		A

Typical Performance Characteristics


50A 1200V Trench Fieldstop IGBT with anti-parallel diode SRE50N120FSUD9
Figure 7: Typical Output Characteristics

 $I_C = f(V_{CE}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GE}$
Figure 8: Typical Output Characteristics

 $I_C = f(V_{CE}); T_j = 175^\circ\text{C}; \text{parameter: } V_{GE}$
Figure 9: Typical transfer characteristic

 $I_C = f(V_{GE}); V_{CE} = 20\text{V}$
Figure 10: Typical collector-emitter saturation voltage as a function of junction temperature

 $V_{CE} = f(T_j); V_{GE} = 15\text{V}$

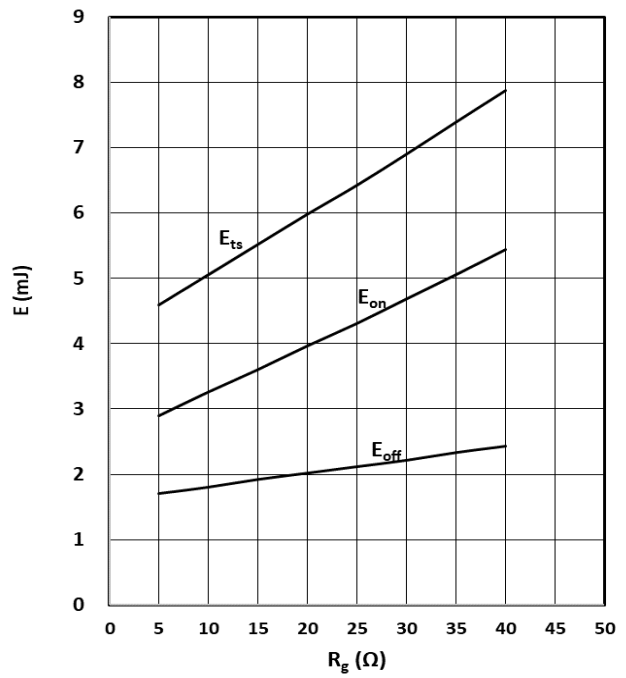
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Figure 11: Typical switching energy losses as a function of collector current



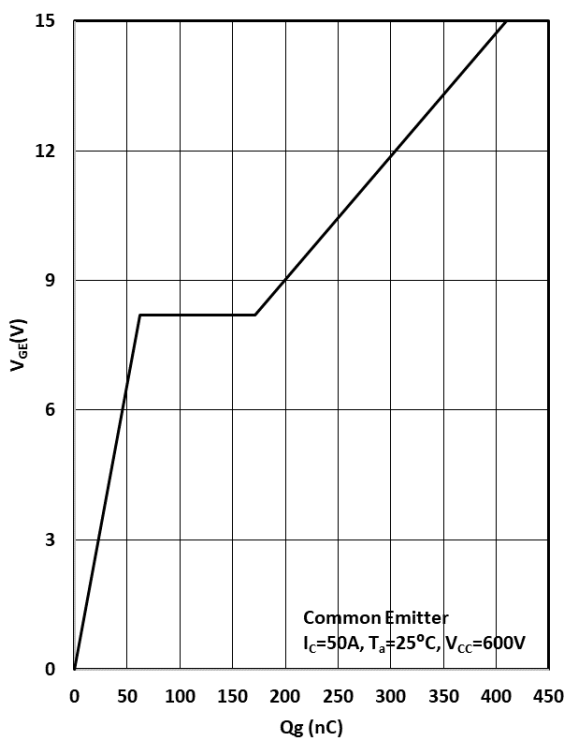
$$E=f(I_c) ; V_{CE}=600V; T_j=25^{\circ}C; R_G=10\Omega$$

Figure 12: Typical switching energy losses as a function of gate resistor



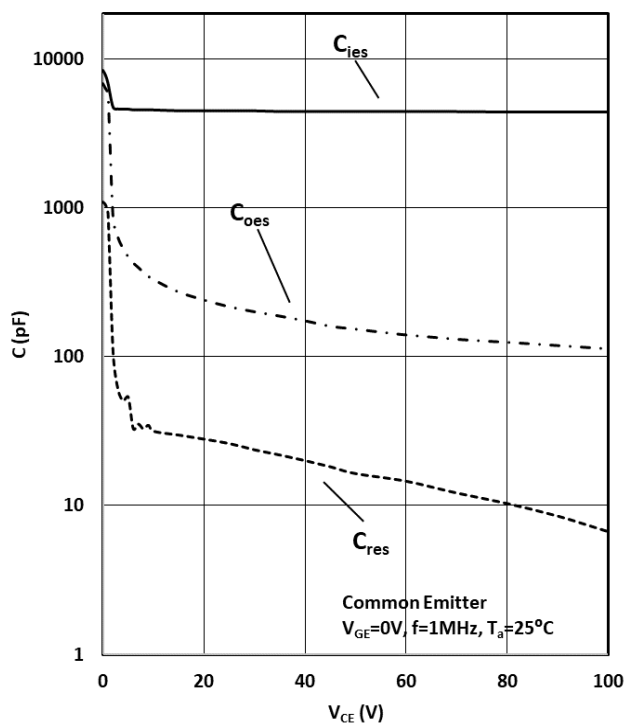
$$E=f(R_G) ; V_{CE}=600V; T_j=25^{\circ}C; I_C=50A$$

Figure 13: Typical Gate Charge



$$V_{GE}=f(Q_g), I_C=50A$$

Figure 14: Typical Capacitances



$$C=f(V_{CE}); V_{GE}=0; f=1MHz$$

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Figure 15: Gate-emitter threshold voltage as a function of junction temperature

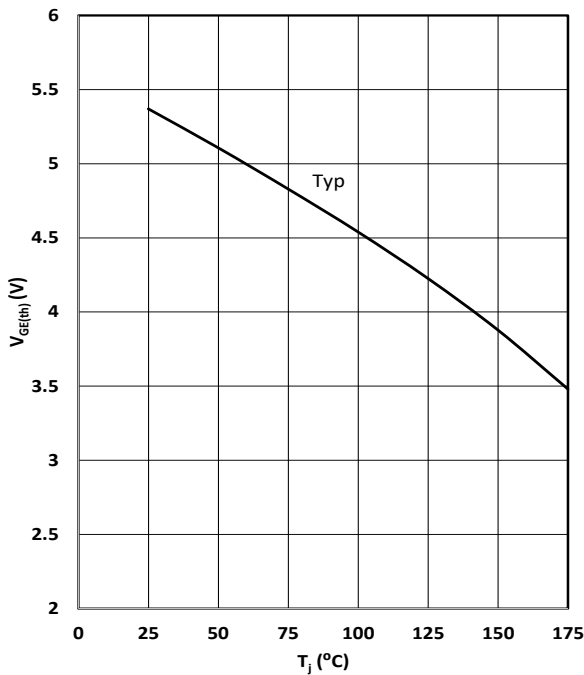

 $I_C = 1.6\text{mA}; V_{GE} = f(T_j)$

Figure 16: Typical diode forward current as a function of forward voltage

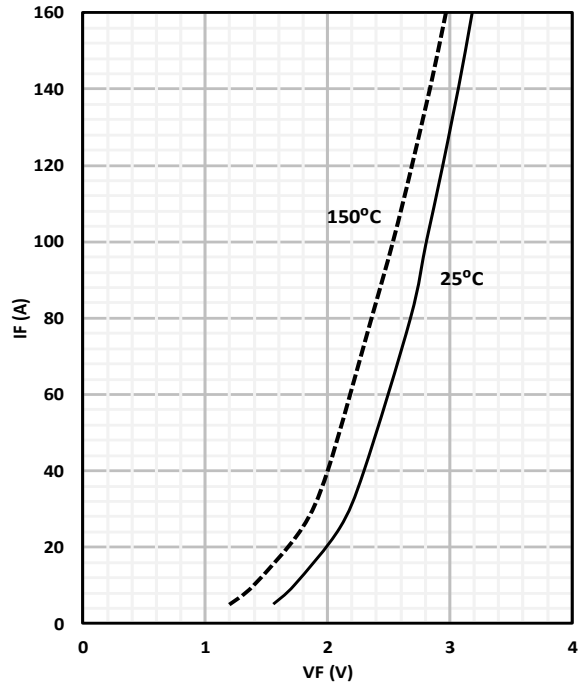
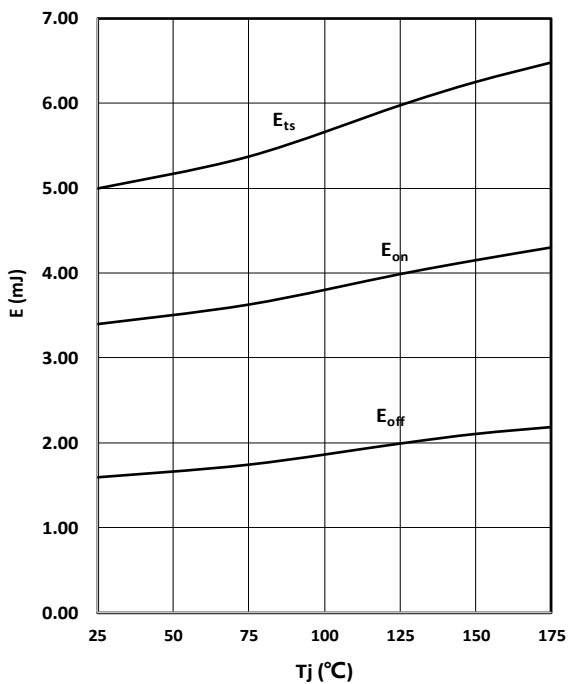
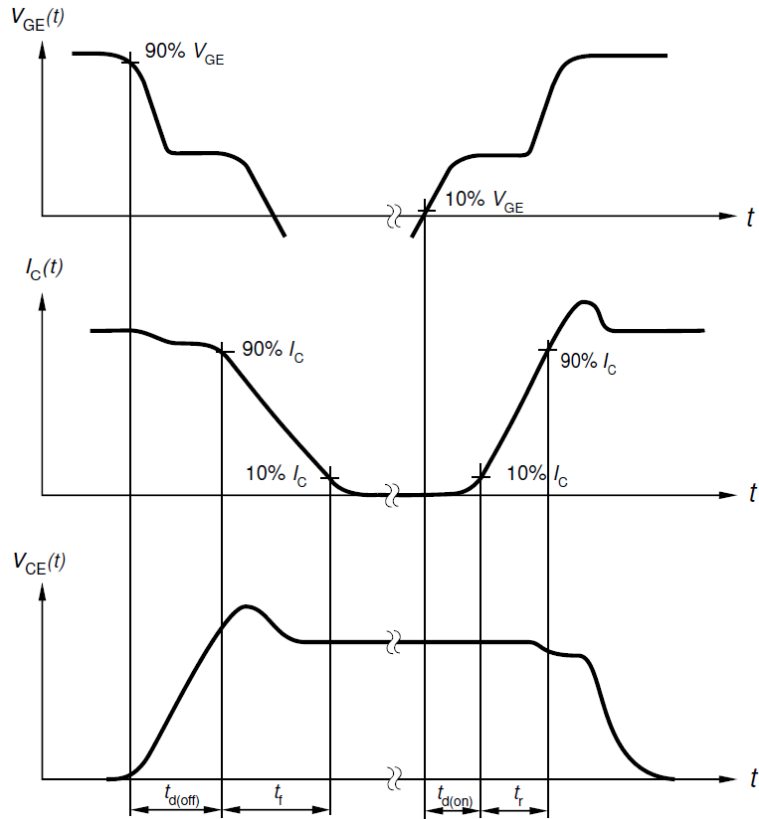
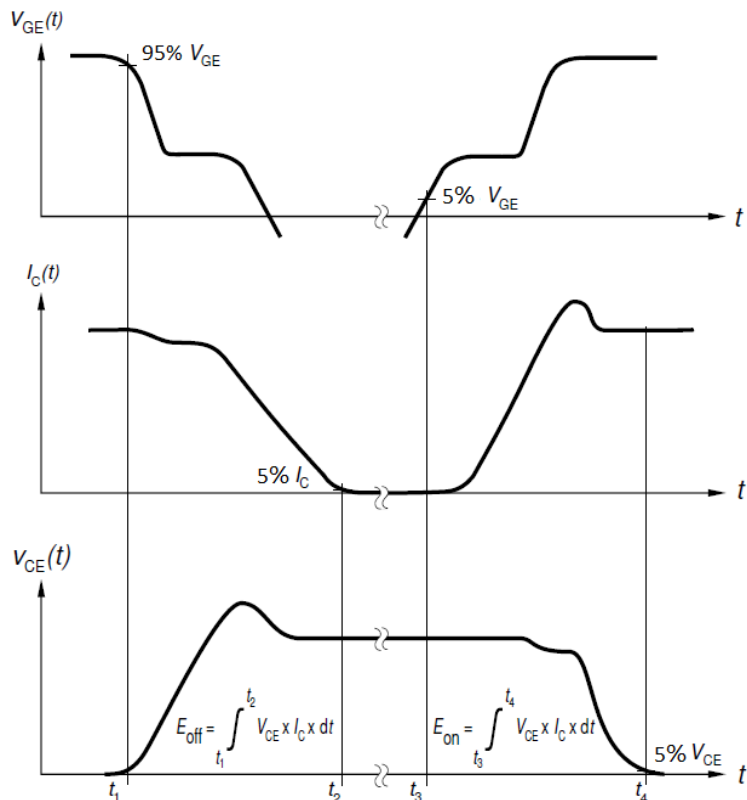
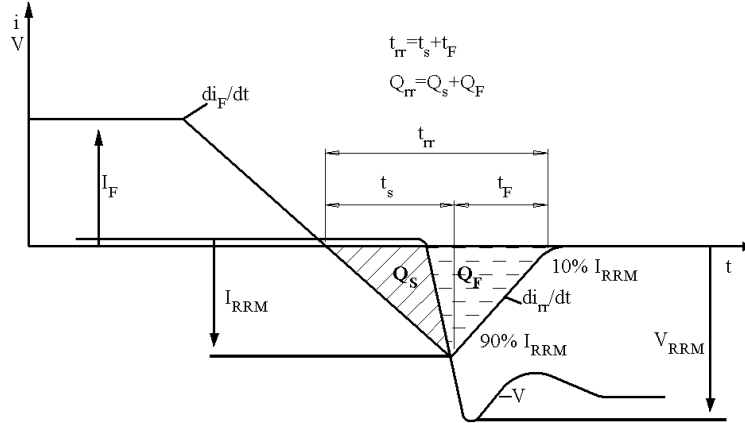

 $V_F = f(I_F);$

Figure 17: Typical switching energy losses as a function of junction temperature

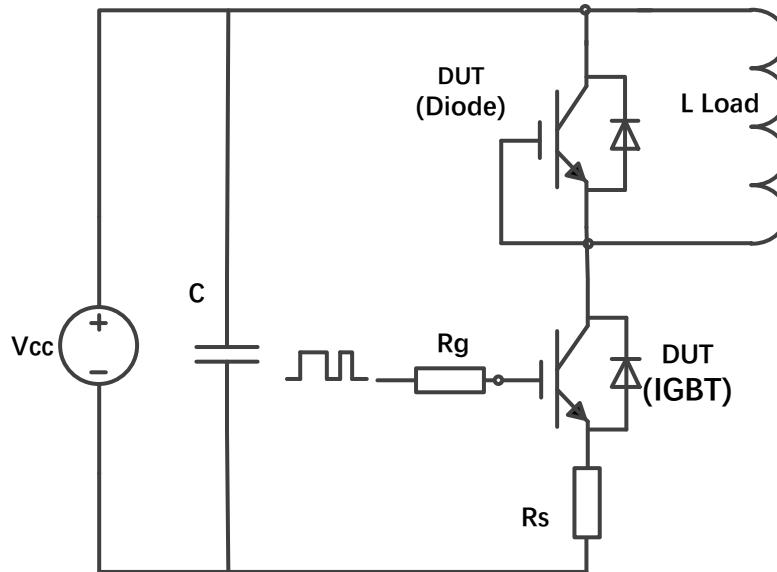

 $E = f(T_j); V_{CE} = 600\text{V}; I_C = 50\text{A}; R_G = 10\Omega$

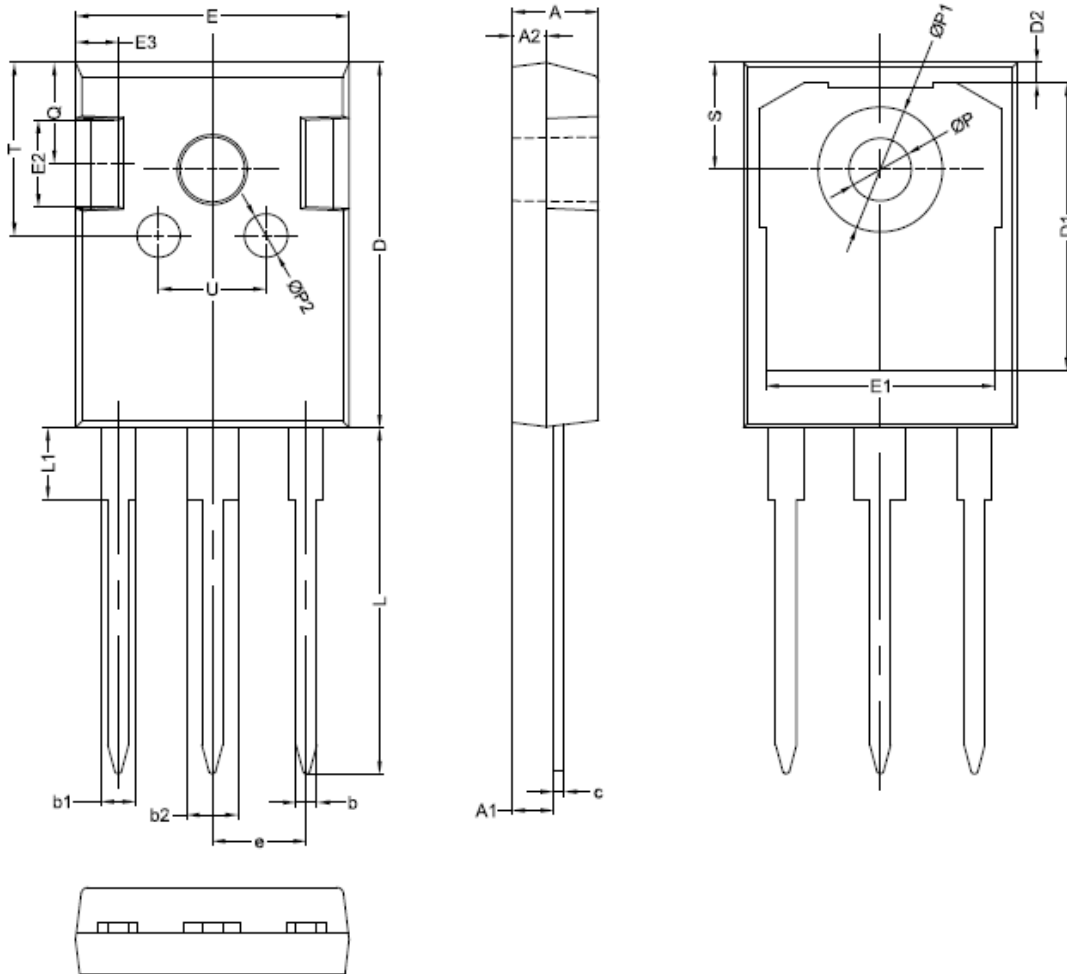
Test Circuits
1. Definition Switching times

2. Definition Switching losses


3. Definition Diode Switching Characteristics



4. Dynamic test circuit



Mechanical Dimensions
TO-247
Unit: mm


Symbol	Dimensions(mm)			Symbol	Dimensions(mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.80	5.00	5.20	E2	-	5.00	-
A1	2.21	2.41	2.61	E3	-	2.50	-
A2	1.90	2.00	2.10	e	5.44(BSC)		
b	1.10	1.20	1.35	L	19.42	19.92	20.42
b1	-	2.00	-	L1	-	4.13	-
b2	-	3.00	-	P	3.50	3.60	3.70
c	0.55	0.60	0.75	P1	-	-	7.40
D	20.80	21.00	21.20	P2	-	2.50	-
D1	-	16.55	-	Q	-	5.80	-
D2	-	1.20	-	S	6.05	6.15	6.25
E	15.60	15.80	16.00	T	-	10.00	-
E1	-	13.30	-	U	-	6.20	-



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